

Cleaning for UHV/XHV at Daresbury Laboratory

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Outline

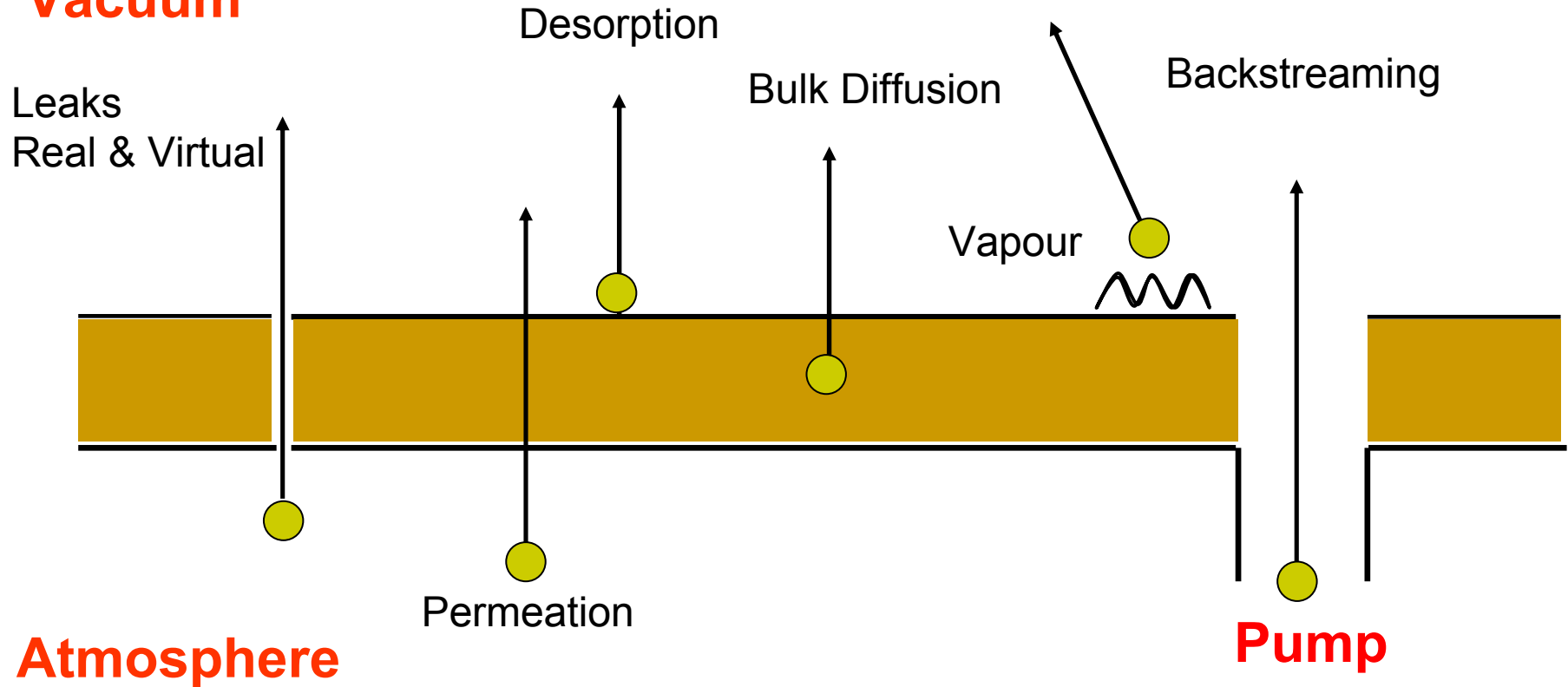
- Cleaning – Why?
- Brief Review of Cleaning Methods Available
- Development of Cleaning Processes at Daresbury Laboratory
- Latest Results of Recent Investigation
- Current and Future Challenges – eXtreme High Vacuum (XHV)

Cleaning – Why?

- **It's all about the end product, what do we want to achieve....**
 - **Particles to pass through accelerator WITHOUT scattering**
 - Maintain Satisfactory Lifetime Stored Electron Beam
 - **Electron Scatter \propto Atomic Number²**
 - **Reduce Outgassing Rates - Low Presence of High Mass Species**
 - Hydrocarbons < 0.1% Pump Lubricants < 0.01%
 - **Stimulated desorption – Usually the MAJOR Gas Load**
 - Photon Stimulated **Desorption** (PSD)
 - Electron Stimulated **Desorption** (ESD)
 - Ion Impact **Desorption**
 - Increased Thermal **Desorption**
 - **Maintain Clean In-Vacuum Surfaces**
 - Coating Deposition
 - Prevent Particle Target Poisoning
 - Maintain Efficient Optical Properties for EM Radiation Transport
- 👉 **Cleanliness is an 'Essential Step' in achieving this**

Sources of Residual Gas

Vacuum



So to Reduce Residual Gas, we must Inhibit or Reduce these processes

Broad Range of Methods Available

Chemical	Thermal Treatment	Polishing	In-Situ Treatment	Others...
Wash – Detergent or Solvent	Vacuum Bakeout	Electro-Polish	Vacuum Bakeout	Bead Blasting
Ultrasonic – Aqueous or Solvent	Vacuum Fire (typical ~950C for STST)	Diamond Paste Machine/Manual	UV Lamps	CO2 Snow
Vapour Clean- Solvent	Air Bake (up to ~ 400C)	Plasma Etch	Glow Discharge	
ACID Etch – Pickling or Passivation	Vacuum Remelt	Diamond Turning	Chemical	
Power Wash – Water Jet		BCP-Buffered Chemical Polishing		

Selecting A Cleaning Method

- Can be difficult....
 - Conflicting views
 - Legislation varies country to country
 - Cost
- So what often happens?
 - A. Copy** an **existing proven method** from elsewhere.
 - B. Develop a cleaning recipe** that is Practical & Economic but **Conservative** (Belt and Braces)
- When a cleaning process works it's usually **'Set In Stone'** , sometimes for many years without investigation!

Daresbury Cleaning History

Originally

- **CERN UHV Procedures Sufficient** (Ultrasonic and Vapour Cleaning)
 - Trichloroethane
 - CFC113 (Freon)
- **Alkaline Degreasing** (Almeco/CERN)
- **Glow Discharge** (added following research at Liverpool University)

1990's

- **Research Study to find alternative solution due to Environmental Protection Legislation (e.g. Kyoto Protocol)**
 - Restricted use of Ozone depleting chemicals
 - Restriction then Ban of Trichloroethane and CFC113

Research Summary

- ✓ **Trichloroethylene** selected (comparable to Trichloroethane)
- ✗ **Aqueous** cleaners NOT SUFFICIENT alone but OK in combination with solvent.
- ✓ **Glow Discharge** – Dropped

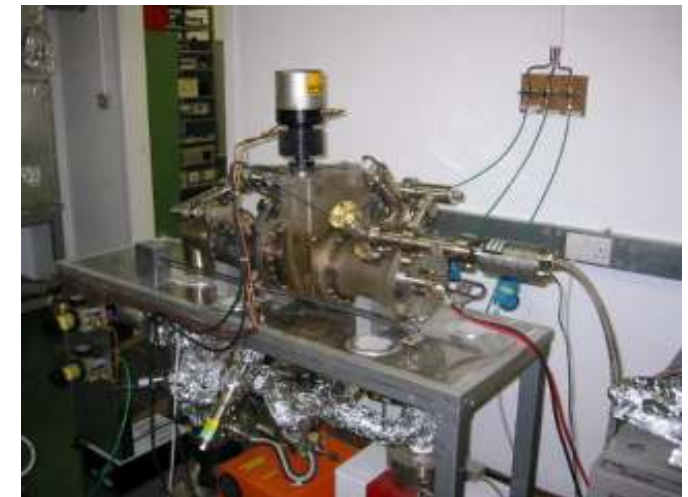
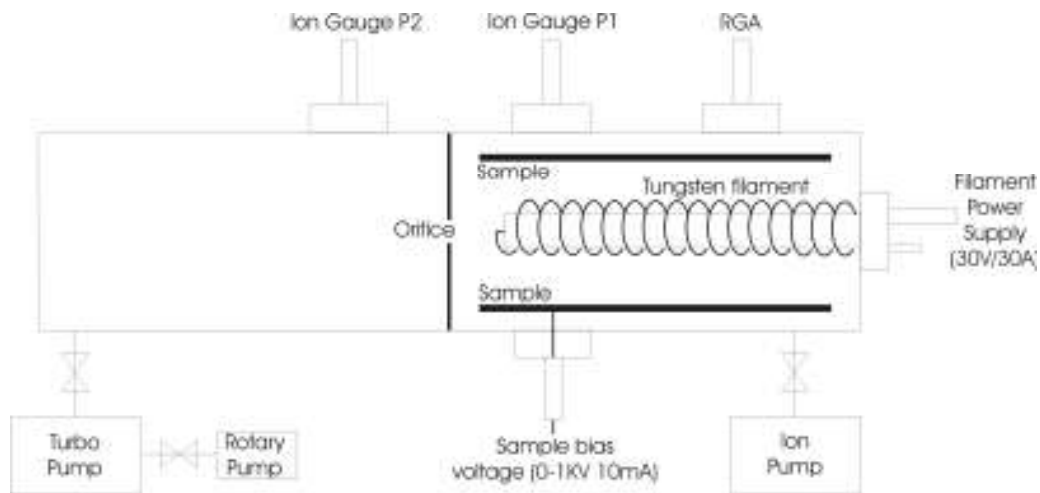
Daresbury Cleaning History

2000's

- Tighter Environmental Protection **Legislation** and New H&S Legislation for VOC's, SED and COSHH
 - ☹ Restricted Use & Emissions for all VOC's under SED
 - ☹ Trichloroethylene re-classified as a Class 2 carcinogen.
 - ☹ Tighter Restrictions on use of Trichloroethylene!
- New research programme started to find suitable alternative

Replacement of Trichloroethylene

- What is important to us? - Thermal outgassing and Stimulated Desorption



$$Q = \frac{P1 - P2}{A} \cdot C$$

- Comparative Tests - existing procedure proven for 20 years

A Selection of Cleaning Agents Tested

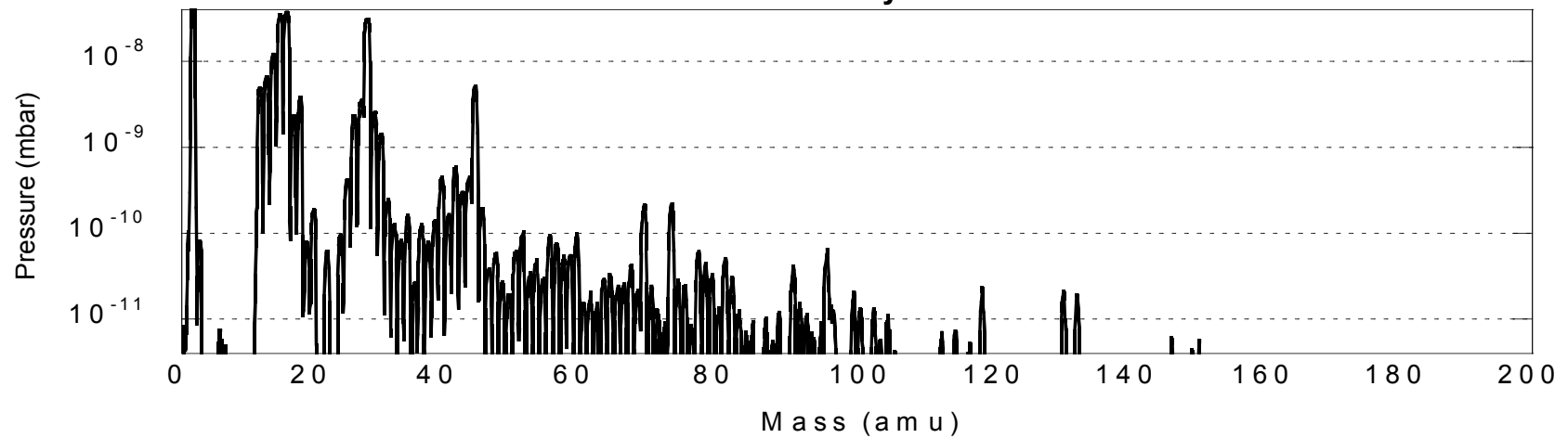
- n-propyl bromide - LEKSOL **Bromine Based**
- n-propyl bromide - LENIUM
- Hydrofluoroether – **HFE-72 DE** (>20 test runs) **HFE**
- Isopropyl Alcohol **Alcohol**
- Aqueous Cleaner 1 - MICRO 90
- Aqueous Cleaner 2 - LANCERCLEAN **Aqueous**
- Aqueous Cleaner 3 - BANNERCLEAN
- Methylene Chloride **Stable Chlorinated**
- Co-Solvent (HFE71 + 1,2 trans-dichloroethylene) -
- Co-Solvent (HFE71 + Isopropyl alcohol) **Co-Solvent**

Cleaning Project Results

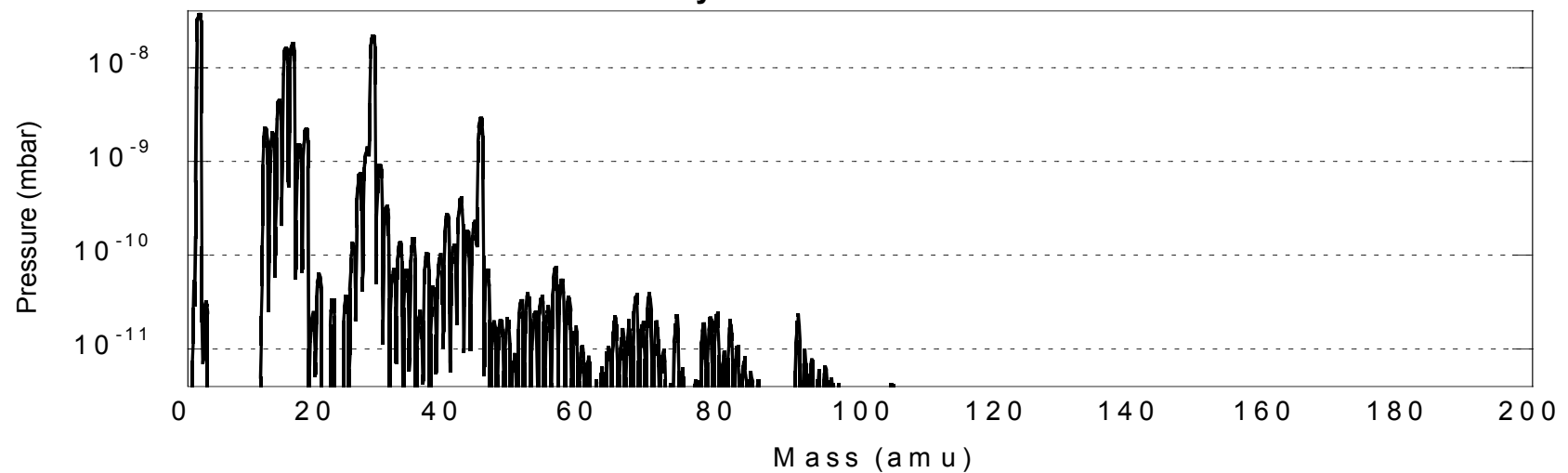
Cleaning Agent	Net thermal outgassing rate due to residual contaminants ($\text{mbar l s}^{-1} \text{ cm}^{-2}$)	Hydrocarbon contamination (%)	Ratio of Mass 69 to Mass 28	Pressure rise from ESD (mbar)	Desorption Yield (molecules/electron)
Blank Run (No sample)	$8.2 \times 10^{-13} \pm 5.8 \times 10^{-13}$	0.46	1.8×10^{-4}	-	-
Trichloroethylene (No contamination)	$<2 \times 10^{-12}$	0.58	3.2×10^{-4}	-	-
Trichloroethylene (No contamination)	$<2 \times 10^{-12}$	0.53	8.3×10^{-4}	-	-
Trichloroethylene (Full contamination)	$<2 \times 10^{-12}$	0.90	8.5×10^{-4}	6.3×10^{-6}	0.055
Trichloroethylene (Full contamination)	$<2 \times 10^{-12}$	0.92	5.8×10^{-4}	-	-
n-propyl bromide 1 – Manufacturer 1	$<2 \times 10^{-12}$	1.34	6.1×10^{-4}	3.6×10^{-6}	0.29
n-propyl bromide 2 – Manufacturer 2	$6 \times 10^{-12} \pm 2 \times 10^{-12}$	2.52	1.9×10^{-2}	2.7×10^{-5}	2.19
Hydrofluoroether – Experiment 1	$<2 \times 10^{-12}$	0.52	4.3×10^{-4}	2.1×10^{-7}	0.017
Hydrofluoroether – Experiment 2	$<2 \times 10^{-12}$	0.86	2.7×10^{-4}	-	-
Isopropyl alcohol	$<2 \times 10^{-12}$	0.93	1.0×10^{-3}	4.3×10^{-6}	0.35
Aqueous cleaner 1	$<2 \times 10^{-12}$	2.86	1.6×10^{-3}	5.5×10^{-5}	4.46
Aqueous cleaner 2	$1.2 \times 10^{-11} \pm 2 \times 10^{-12}$	2.03	1.93×10^{-3}	3.7×10^{-5}	2.99
Aqueous cleaner 3	$<2 \times 10^{-12}$	2.70	2.2×10^{-3}	2.6×10^{-5}	2.12

ESD RGA data for HFE and Trike

Trichloroethylene

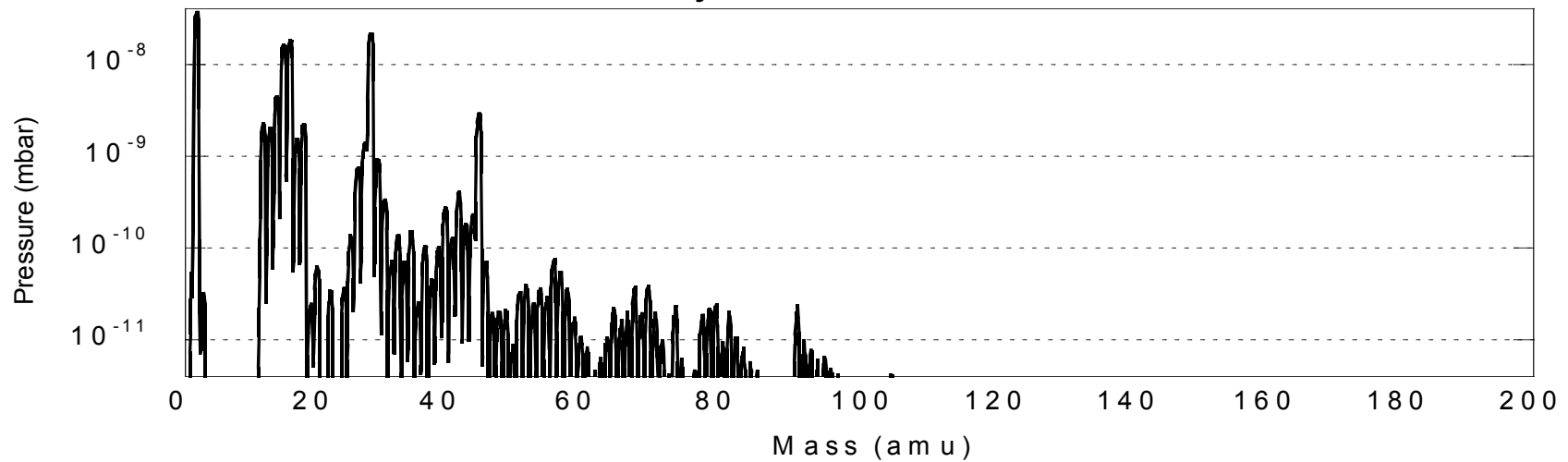


Hydrofluoroether

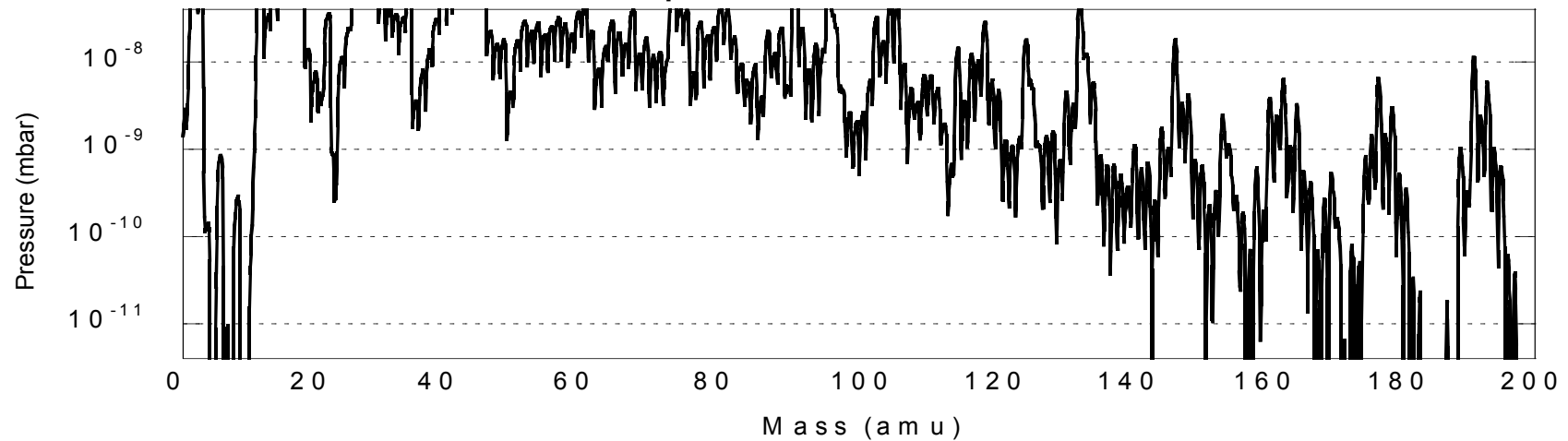


ESD RGA data for Aqueous and Solvent (HFE)

Hydrofluoroether

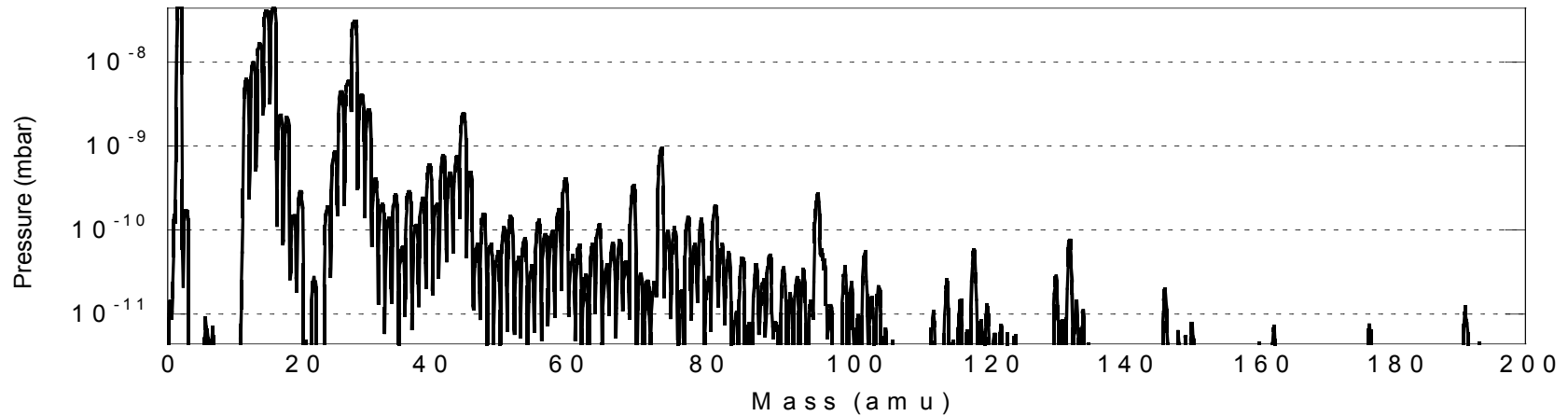


Aqueous Cleaner 1

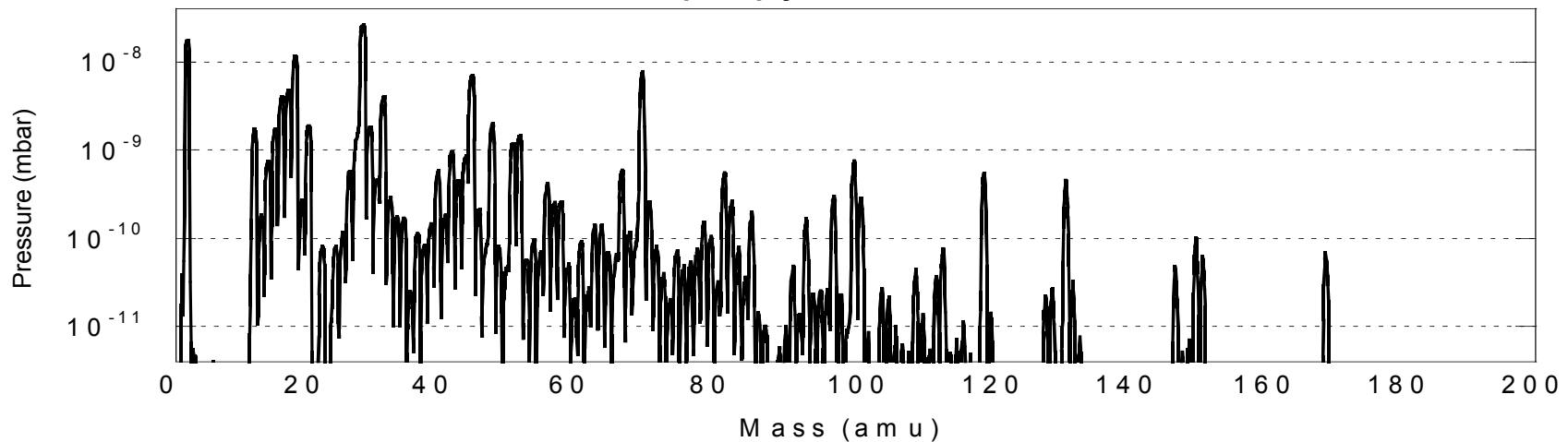


Cleaning Project ESD Results – N-propyl bromides

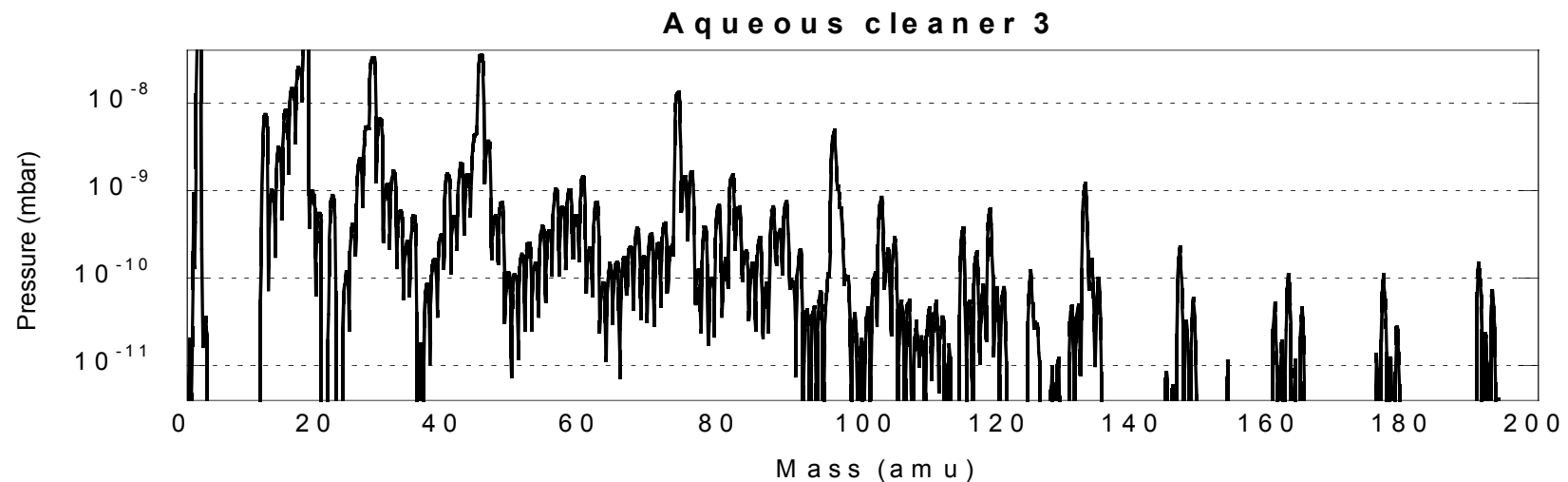
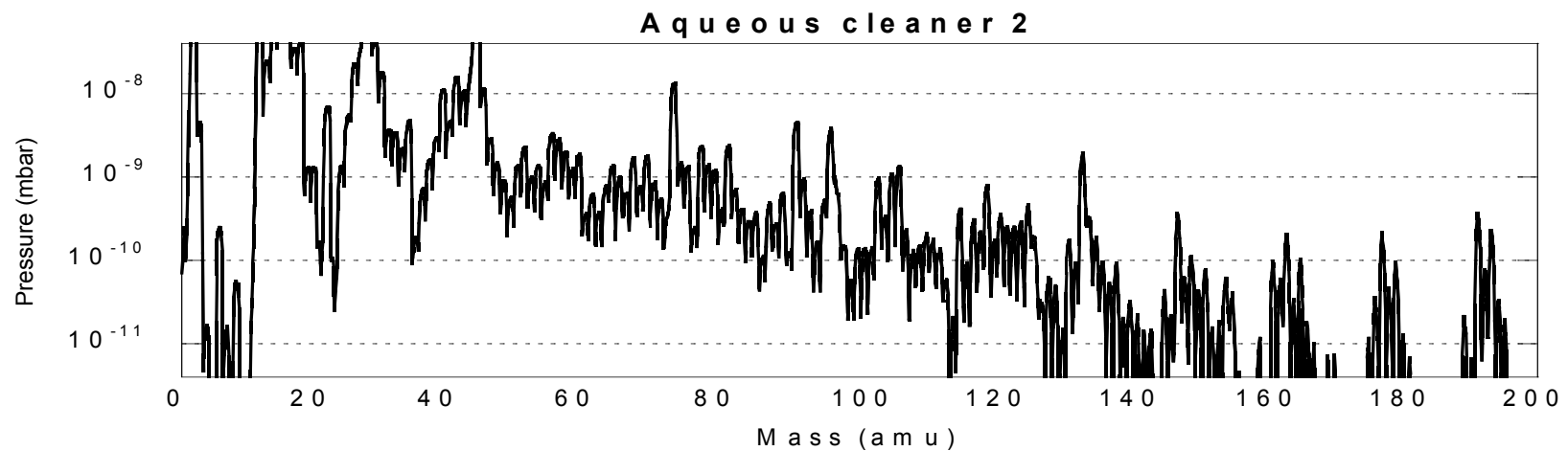
N-propyl bromide 1



N-propyl bromide 2



Cleaning Project ESD Results – Aqueous Cleaners

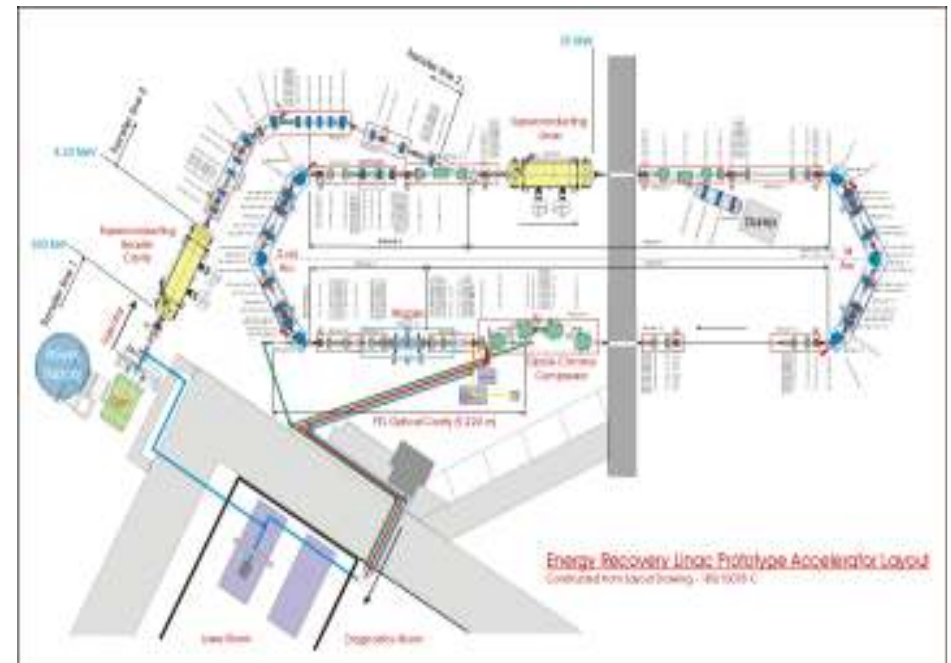


Summary of Findings

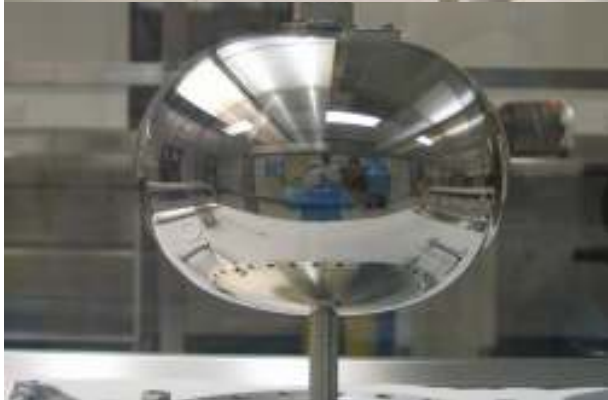
- Some Modern **Aqueous Cleaners** clean as well as solvents when considering Room Temperature Outgassing
- **ESD Data** – Solvents Much Better
- **HFE** (Hydrofluoroether – 3M™ Novec™) – Preferred Trike replacement
- Reference:- Phase 1 – **Vacuum 81 (2007) 793-798** *
Phase 2 – In Print

Current and Future Challenges

- Currently Developing XHV and Low Particle Processing Techniques
 - Use of SRF ($P_T < 10^{-10}$ mbar, low levels of particles and surface contaminants)
 - Requirements for High Average Current Photoinjectors ($P_T < 10^{-11}$ mbar, $P_{O_2} < 10^{-14}$ mbar, low levels of particles and surface contaminants)
 - **Reduce gas density in region of photo-injector**
 - E.g. To reduce **ion back bombardment** on photocathode material and to prevent **cathode poisoning**. May lead to reduced QE.



Particle Control



Particle Control

- Systems of flushing and counting particles
- Use of Clean Hoods and Clean Rooms
- Careful Design to Minimize Particle Sources or Position Them Safely away from Beam.
- Careful Selection of in-vacuum components
- Use of gas filters during let up
- Controlled gas flow (pump down/letup speed)
- **Good Cleaning Procedures (HFE)**

Summary

- Why cleaning is so important for UHV/XHV
- Historical look at cleaning here at Daresbury
- Results of recent studies show solvents are a much better solution than aqueous cleaners for our application.
- Introduced particle control procedures.
- XHV requirements for a GaAs photocathode.
- Particle control for superconducting cavities.